

Major Terms of the HKMC's HKD Benchmark Bond Issuance

Issuer:	The Hong Kong Mortgage Corporation Limited		
Issue Rating:	AA+ (S&P) / Aa3 (Moody's)		
Issue Size:	HK\$8 billion	HK\$3 billion	HK\$1 billion
Issue Date:	28 February 2024	28 February 2024	28 February 2024
Maturity Date:	28 February 2026	28 February 2029	28 February 2034
Tenor:	2 years	5 years	10 years
Yield:	4.25% per annum	4.10% per annum	4.20% per annum
Status:	Senior and unsecured		
Listing:	The Stock Exchange of Hong Kong Limited		
Clearing:	Central Moneymarkets Unit (CMU) with links to Euroclear / Clearstream		
Use of Proceeds:	The net proceeds of the notes issued will be used to meet general financing requirements		
Joint Global Coordinators, Joint Bookrunners and Joint Lead Managers:	Bank of China (Hong Kong) Crédit Agricole CIB HSBC Standard Chartered Bank		
Joint Bookrunners and Joint Lead Managers:	ANZ BNP PARIBAS China Construction Bank (Asia) Citigroup DBS Bank Ltd. ICBC (Asia) Mizuho United Overseas Bank		
Joint Lead Managers:	Bank of Communications Barclays China CITIC Bank International China International Capital Corporation J.P. Morgan Morgan Stanley OCBC SMBC Nikko		